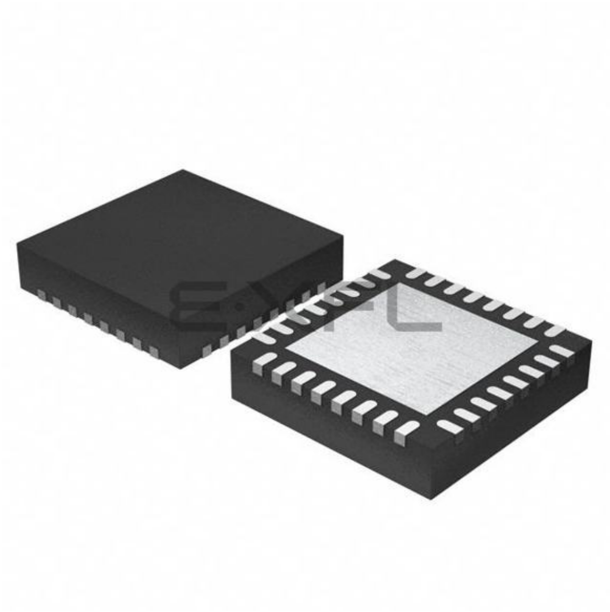
Infineon Technologies - CY8C4024LQI-S412T Datasheet



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What is "Embedded - Microcontrollers"?

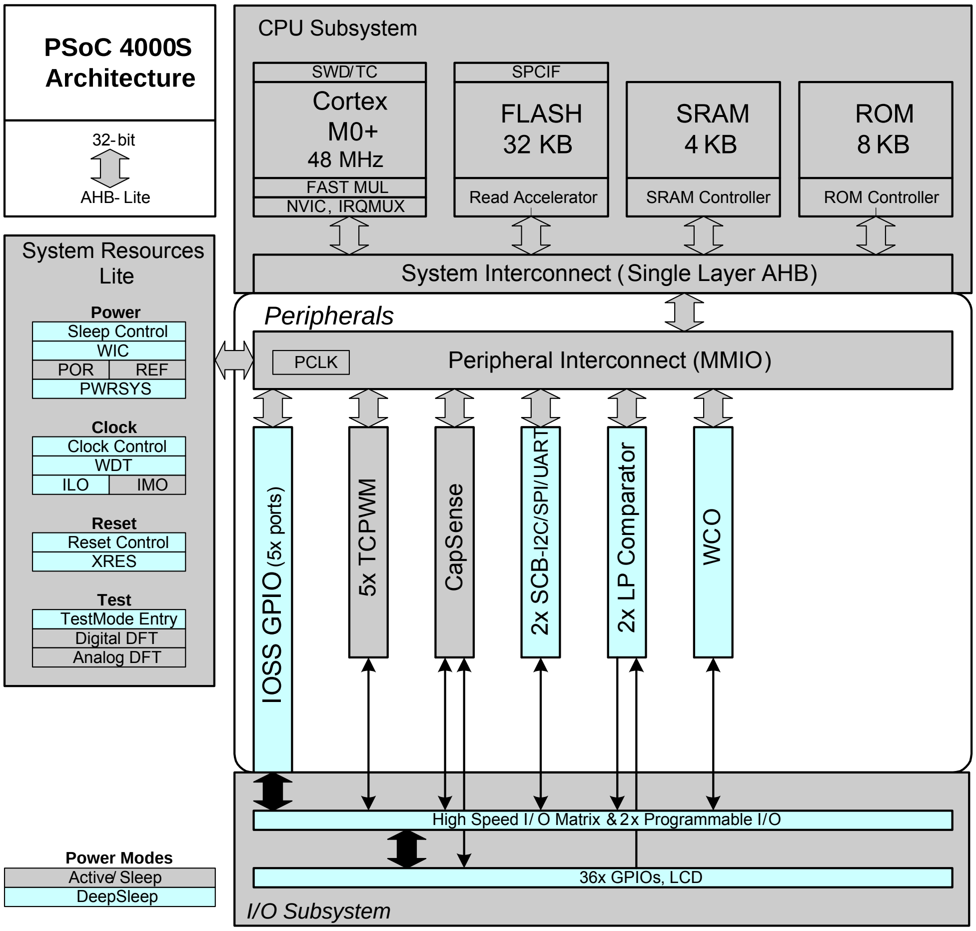
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	24MHz
Connectivity	I²C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, CapSense, LCD, LVD, POR, PWM, WDT
Number of I/O	27
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-UFQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4024lqi-s412t

Contents

Figure 1. Block Diagram



PSoC 4000S devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware.

The ARM Serial-Wire Debug (SWD) interface supports all programming and debug features of the device.

Complete debug-on-chip functionality enables full-device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator IDE provides fully integrated programming and debug support for the PSoC 4000S devices. The SWD interface is fully compatible with industry-standard third-party tools. The PSoC 4000S family provides a level of security not possible with multi-chip application solutions or with microcontrollers. It has the following advantages:

- Allows disabling of debug features
- Robust flash protection
- Allows customer-proprietary functionality to be implemented in on-chip programmable blocks

The debug circuits are enabled by default and can be disabled in firmware. If they are not enabled, the only way to re-enable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables debugging. Thus firmware control of debugging cannot be over-ridden without erasing the firmware thus providing security.

Additionally, all device interfaces can be permanently disabled (device security) for applications concerned about phishing attacks due to a maliciously reprogrammed device or attempts to defeat security by starting and interrupting flash programming sequences. All programming, debug, and test interfaces are disabled when maximum device security is enabled. Therefore, PSoC 4000S, with device security enabled, may not be returned for failure analysis. This is a trade-off the PSoC 4000S allows the customer to make.

GPIO

The PSoC 4000S has up to 36 GPIOs. The GPIO block implements the following:

- Eight drive modes:
  - Analog input mode (input and output buffers disabled)
  - Input only
  - Weak pull-up with strong pull-down
  - Strong pull-up with weak pull-down
  - Open drain with strong pull-down
  - Open drain with strong pull-up
  - Strong pull-up with strong pull-down
  - Weak pull-up with weak pull-down
- Input threshold select (CMOS or LVTTL).
- Individual control of input and output buffer enabling/disabling in addition to the drive strength modes
- Selectable slew rates for dV/dt related noise control to improve EMI

The pins are organized in logical entities called ports, which are 8-bit in width (less for Ports 2 and 3). During power-on and reset, the blocks are forced to the disable state so as not to crowbar any inputs and/or cause excess turn-on current. A multiplexing network known as a high-speed I/O matrix is used to multiplex between various signals that may connect to an I/O pin.

Data output and pin state registers store, respectively, the values to be driven on the pins and the states of the pins themselves.

Every I/O pin can generate an interrupt if so enabled and each I/O port has an interrupt request (IRQ) and interrupt service routine (ISR) vector associated with it (5 for PSoC 4000S).

Special Function Peripherals

CapSense

CapSense is supported in the PSoC 4000S through a CapSense Sigma-Delta (CSD) block that can be connected to any pins through an analog multiplex bus via analog switches. CapSense function can thus be provided on any available pin or group of pins in a system under software control. A PSoC Creator component is provided for the CapSense block to make it easy for the user.

Shield voltage can be driven on another analog multiplex bus to provide water-tolerance capability. Water tolerance is provided by driving the shield electrode in phase with the sense electrode to keep the shield capacitance from attenuating the sensed input. Proximity sensing can also be implemented.

The CapSense block has two IDACs, which can be used for general purposes if CapSense is not being used (both IDACs are available in that case) or if CapSense is used without water tolerance (one IDAC is available).

The CapSense block also provides a 10-bit Slope ADC function, which can be used in conjunction with the CapSense function.

The CapSense block is an advanced, low-noise, programmable block with programmable voltage references and current source ranges for improved sensitivity and flexibility. It can also use an external reference voltage. It has a full-wave CSD mode that alternates sensing to VDDA and Ground to null out power-supply related noise.

LCD Segment Drive

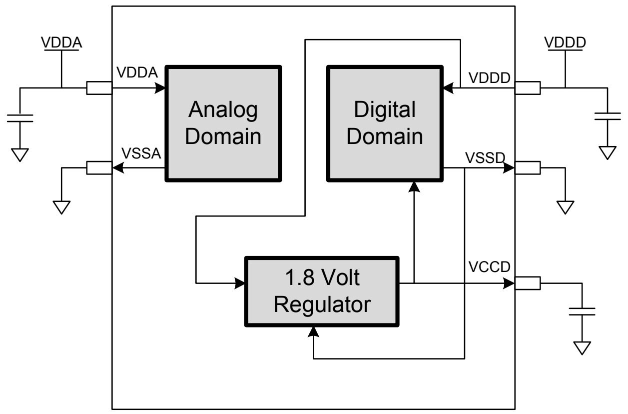
The PSoC 4000S has an LCD controller, which can drive up to 8 commons and up to 28 segments. It uses full digital methods to drive the LCD segments requiring no generation of internal LCD voltages. The two methods used are referred to as Digital Correlation and PWM. Digital Correlation pertains to modulating the frequency and drive levels of the common and segment signals to generate the highest RMS voltage across a segment to light it up or to keep the RMS signal to zero. This method is good for STN displays but may result in reduced contrast with TN (cheaper) displays. PWM pertains to driving the panel with PWM signals to effectively use the capacitance of the panel to provide the integration of the modulated pulse-width to generate the desired LCD voltage. This method results in higher power consumption but can result in better results when driving TN displays. LCD operation is supported during Deep Sleep refreshing a small display buffer (4 bits; 1 32-bit register per port).

Port/ Pin	Analog	Smart I/O	Alternate Function 1	Alternate Function 2	Alternate Function 3	Deep Sleep 1	Deep Sleep 2
P1.6							scb[0].spi_select3:1
P1.7							
P2.0		prgio[0].io[0]	tcpwm.line[4]:0	csd.comp	tcpwm.tr_in[4]	scb[1].i2c_scl:1	scb[1].spi_mosi:2
P2.1		prgio[0].io[1]	tcpwm.line_compl[4]:0		tcpwm.tr_in[5]	scb[1].i2c_sda:1	scb[1].spi_miso:2
P2.2		prgio[0].io[2]					scb[1].spi_clk:2
P2.3		prgio[0].io[3]					scb[1].spi_select0:2
P2.4		prgio[0].io[4]	tcpwm.line[0]:1				scb[1].spi_select1:1
P2.5		prgio[0].io[5]	tcpwm.line_compl[0]:1				scb[1].spi_select2:1
P2.6		prgio[0].io[6]	tcpwm.line[1]:1				scb[1].spi_select3:1
P2.7		prgio[0].io[7]	tcpwm.line_compl[1]:1			lpcomp.comp[0]:1	
P3.0		prgio[1].io[0]	tcpwm.line[0]:0	scb[1].uart_rx:1		scb[1].i2c_scl:2	scb[1].spi_mosi:0
P3.1		prgio[1].io[1]	tcpwm.line_compl[0]:0	scb[1].uart_tx:1		scb[1].i2c_sda:2	scb[1].spi_miso:0
P3.2		prgio[1].io[2]	tcpwm.line[1]:0	scb[1].uart_cts:1		cpuss.swd_data	scb[1].spi_clk:0
P3.3		prgio[1].io[3]	tcpwm.line_compl[1]:0	scb[1].uart_rts:1		cpuss.swd_clk	scb[1].spi_select0:0
P3.4		prgio[1].io[4]	tcpwm.line[2]:0		tcpwm.tr_in[6]		scb[1].spi_select1:0
P3.5		prgio[1].io[5]	tcpwm.line_compl[2]:0		tcpwm.tr_in[7]		scb[1].spi_select2:0
P3.6		prgio[1].io[6]	tcpwm.line[3]:0		tcpwm.tr_in[8]		scb[1].spi_select3:0
P3.7		prgio[1].io[7]	tcpwm.line_compl[3]:0		tcpwm.tr_in[9]	lpcomp.comp[1]:1	
P4.0	csd.vref_ext			scb[0].uart_rx:0	tcpwm.tr_in[10]	scb[0].i2c_scl:1	scb[0].spi_mosi:0
P4.1	csd.cshieldpads			scb[0].uart_tx:0	tcpwm.tr_in[11]	scb[0].i2c_sda:1	scb[0].spi_miso:0
P4.2	csd.cmodpad			scb[0].uart_cts:0		lpcomp.comp[0]:0	scb[0].spi_clk:0
P4.3	csd.csh_tank			scb[0].uart_rts:0		lpcomp.comp[1]:0	scb[0].spi_select0:0

Power

The following power system diagram shows the set of power supply pins as implemented for the PSoC 4000S. The system has one regulator in Active mode for the digital circuitry. There is no analog regulator; the analog circuits run directly from the V_{DD} input.

Figure 3. Power Supply Connections



There are two distinct modes of operation. In Mode 1, the supply voltage range is 1.8 V to 5.5 V (unregulated externally; internal regulator operational). In Mode 2, the supply range is1.8 V ±5% (externally regulated; 1.71 to 1.89, internal regulator bypassed).

Mode 1: 1.8 V to 5.5 V External Supply

In this mode, the PSoC 4000S is powered by an external power supply that can be anywhere in the range of 1.8 to 5.5 V. This range is also designed for battery-powered operation. For example, the chip can be powered from a battery system that starts at 3.5 V and works down to 1.8 V. In this mode, the internal regulator of the PSoC 4000S supplies the internal logic and its output is connected to the V_{CCD} pin. The VCCD pin must be bypassed to ground via an external capacitor (0.1 µF; X5R ceramic or better) and must not be connected to anything else.

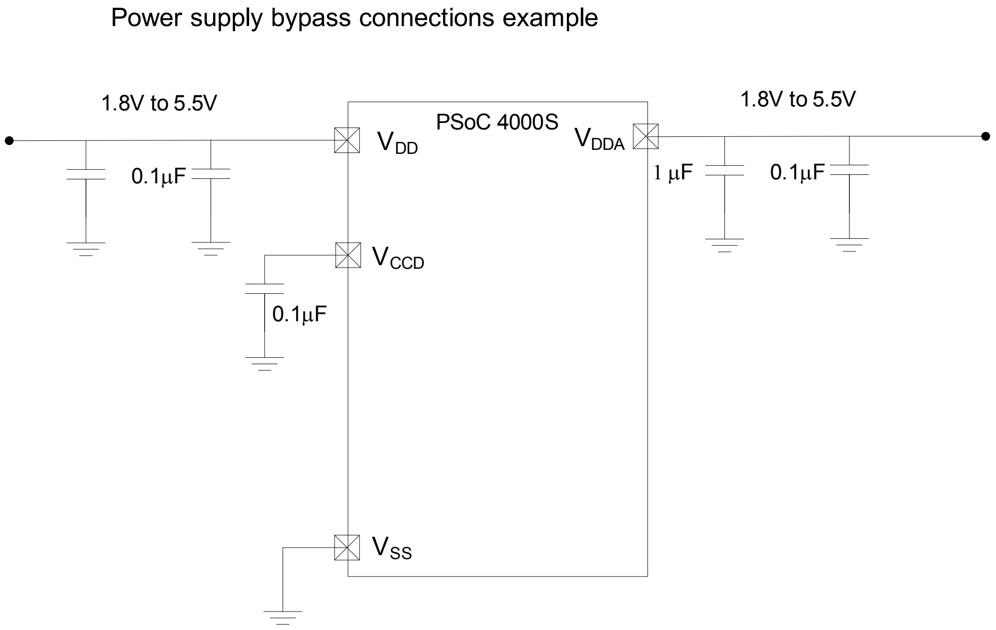
Mode 2: 1.8 V ±5% External Supply

In this mode, the PSoC 4000S is powered by an external power supply that must be within the range of 1.71 to 1.89 V; note that this range needs to include the power supply ripple too. In this mode, the VDD and VCCD pins are shorted together and bypassed. The internal regulator can be disabled in the firmware.

Bypass capacitors must be used from VDDD to ground. The typical practice for systems in this frequency range is to use a capacitor in the 1-µF range, in parallel with a smaller capacitor (0.1 µF, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

An example of a bypass scheme is shown in the following diagram.

Figure 4. External Supply Range from 1.8 V to 5.5 V with Internal Regulator Active



Development Support

The PSoC 4000S family has a rich set of documentation, development tools, and online resources to assist you during your development process. Visit www.cypress.com/go/psoc4 to find out more.

Documentation

A suite of documentation supports the PSoC 4000S family to ensure that you can find answers to your questions quickly. This section contains a list of some of the key documents.

Software User Guide: A step-by-step guide for using PSoC Creator. The software user guide shows you how the PSoC Creator build process works in detail, how to use source control with PSoC Creator, and much more.

Component Datasheets: The flexibility of PSoC allows the creation of new peripherals (components) long after the device has gone into production. Component data sheets provide all of the information needed to select and use a particular component, including a functional description, API documentation, example code, and AC/DC specifications.

Application Notes: PSoC application notes discuss a particular application of PSoC in depth; examples include brushless DC motor control and on-chip filtering. Application notes often include example projects in addition to the application note document.

Technical Reference Manual: The Technical Reference Manual (TRM) contains all the technical detail you need to use a PSoC device, including a complete description of all PSoC registers. The TRM is available in the Documentation section at www.cypress.com/psoc4.

Online

In addition to print documentation, the Cypress PSoC forums connect you with fellow PSoC users and experts in PSoC from around the world, 24 hours a day, 7 days a week.

Tools

With industry standard cores, programming, and debugging interfaces, the PSoC 4000S family is part of a development tool ecosystem. Visit us at www.cypress.com/go/psoccreator for the latest information on the revolutionary, easy to use PSoC Creator IDE, supported third party compilers, programmers, debuggers, and development kits.

Electrical Specifications

Absolute Maximum Ratings

Table 2. Absolute Maximum Ratings[1]

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID1	V_{DDD_ABS}	Digital supply relative to V_{SS}	–0.5	–	6	V	–
SID2	V_{CCD_ABS}	Direct digital core voltage input relative to V_{SS}	–0.5	–	1.95		–
SID3	V_{GPIO_ABS}	GPIO voltage	–0.5	–	V_{DD}+0.5		–
SID4	I_{GPIO_ABS}	Maximum current per GPIO	–25	–	25	mA	–
SID5	$I_{GPIO\_injection}$	GPIO injection current, Max for $V_{IH} > V_{DDD}$, and Min for $V_{IL} < V_{SS}$	–0.5	–	0.5		Current injected per pin
BID44	ESD_HBM	Electrostatic discharge human body model	2200	–	–	V	–
BID45	ESD_CDM	Electrostatic discharge charged device model	500	–	–		–
BID46	LU	Pin current for latch-up	–140	–	140	mA	–

Device Level Specifications

All specifications are valid for –40 °C ≤ T_A ≤ 85 °C and T_J ≤ 100 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

Table 3. DC Specifications

Typical values measured at V_{DD} = 3.3 V and 25 °C.

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID53	V_{DD}	Power supply input voltage	1.8	–	5.5	V	Internally regulated supply
SID255	V_{DD}	Power supply input voltage ($V_{CCD} = V_{DD} = V_{DDA}$)	1.71	–	1.89		Internally unregulated supply
SID54	V_{CCD}	Output voltage (for core logic)	–	1.8	–		–
SID55	C_{EFC}	External regulator voltage bypass	–	0.1	–	µF	X5R ceramic or better
SID56	C_{EXC}	Power supply bypass capacitor	–	1	–		X5R ceramic or better
Active Mode, V_{DD} = 1.8 V to 5.5 V. Typical values measured at VDD = 3.3 V and 25 °C.							
SID10	I_{DD5}	Execute from flash; CPU at 6 MHz	–	1.2	2.0	mA	–
SID16	I_{DD8}	Execute from flash; CPU at 24 MHz	–	2.4	4.0		–
SID19	I_{DD11}	Execute from flash; CPU at 48 MHz	–	4.6	5.9		–
Sleep Mode, VDDD = 1.8 V to 5.5 V (Regulator on)							
SID22	I_{DD17}	I^2C wakeup WDT, and Comparators on	–	1.1	1.6	mA	6 MHz
SID25	I_{DD20}	I^2C wakeup, WDT, and Comparators on	–	1.4	1.9		12 MHz

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Note

1. Usage above the absolute maximum conditions listed in Table 2 may cause permanent damage to the device. Exposure to Absolute Maximum conditions for extended periods of time may affect device reliability. The Maximum Storage Temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature Storage Life. When used below Absolute Maximum conditions but above normal operating conditions, the device may not operate to specification.

Analog Peripherals

Table 9. Comparator DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID84	$V_{OFFSET1}$	Input offset voltage, Factory trim	–	–	±10	mV	–
SID85	$V_{OFFSET2}$	Input offset voltage, Custom trim	–	–	±4		–
SID86	V_{HYST}	Hysteresis when enabled	–	10	35		–
SID87	V_{ICM1}	Input common mode voltage in normal mode	0	–	V_{DDD}-0.1	V	Modes 1 and 2
SID247	V_{ICM2}	Input common mode voltage in low power mode	0	–	V_{DDD}		–
SID247A	V_{ICM3}	Input common mode voltage in ultra low power mode	0	–	V_{DDD}-1.15		$V_{DDD} \geq 2.2$ V at –40 °C
SID88	C_{MRR}	Common mode rejection ratio	50	–	–	dB	$V_{DDD} \geq 2.7V$
SID88A	C_{MRR}	Common mode rejection ratio	42	–	–		$V_{DDD} \leq 2.7V$
SID89	I_{CMP1}	Block current, normal mode	–	–	400	µA	–
SID248	I_{CMP2}	Block current, low power mode	–	–	100		–
SID259	I_{CMP3}	Block current in ultra low-power mode	–	6	28		$V_{DDD} \geq 2.2$ V at –40 °C
SID90	Z_{CMP}	DC Input impedance of comparator	35	–	–	MΩ	–

Table 10. Comparator AC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID91	TRESP1	Response time, normal mode, 50 mV overdrive	–	38	110	ns	–
SID258	TRESP2	Response time, low power mode, 50 mV overdrive	–	70	200		–
SID92	TRESP3	Response time, ultra-low power mode, 200 mV overdrive	–	2.3	15	µs	$V_{DDD} \geq 2.2$ V at –40 °C

I^2C

Table 14. Fixed I^{2}C DC Specifications[7]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID149	I_{I2C1}	Block current consumption at 100 kHz	–	–	50	µA	–
SID150	I_{I2C2}	Block current consumption at 400 kHz	–	–	135		–
SID151	I_{I2C3}	Block current consumption at 1 Mbps	–	–	310		–
SID152	I_{I2C4}	I^{2}C enabled in Deep Sleep mode	–	–	1.4		

Table 15. Fixed I^{2}C AC Specifications[7]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID153	F_{I2C1}	Bit rate	–	–	1	Msps	–

Table 16. SPI DC Specifications[7]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID163	ISPI1	Block current consumption at 1 Mbps	–	–	360	µA	–
SID164	ISPI2	Block current consumption at 4 Mbps	–	–	560		–
SID165	ISPI3	Block current consumption at 8 Mbps	–	–	600		–

Table 17. SPI AC Specifications[7]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID166	FSPI	SPI operating frequency (Master; 6X Oversampling)	–	–	8	MHz	
Fixed SPI Master Mode AC Specifications							
SID167	TDMO	MOSI Valid after SClock driving edge	–	–	15	ns	–
SID168	TDSI	MISO Valid before SClock capturing edge	20	–	–		Full clock, late MISO sampling
SID169	THMO	Previous MOSI data hold time	0	–	–		Referred to Slave capturing edge
Fixed SPI Slave Mode AC Specifications							
SID170	TDMI	MOSI Valid before Sclock Capturing edge	40	–	–	ns	–
SID171	TDSO	MISO Valid after Sclock driving edge	–	–	42 + 3*Tcpu		$T_{CPU} = 1/F_{CPU}$
SID171A	TDSO_EXT	MISO Valid after Sclock driving edge in Ext. Clk mode	–	–	48		–
SID172	THSO	Previous MISO data hold time	0	–	–		–
SID172A	TSSELSSCK	SSEL Valid to first SCK Valid edge	–	–	100	ns	–

Note

[7] Guaranteed by characterization.

Table 18. UART DC Specifications[8]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID160	I_{UART1}	Block current consumption at 100 Kbps	–	–	55	µA	–
SID161	I_{UART2}	Block current consumption at 1000 Kbps	–	–	312	µA	–

Table 19. UART AC Specifications[8]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID162	F_{UART}	Bit rate	–	–	1	Mbps	–

Table 20. LCD Direct Drive DC Specifications[8]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID154	I_{LCDLOW}	Operating current in low power mode	–	5	–	µA	16 × 4 small segment disp. at 50 Hz
SID155	C_{LCDCAP}	LCD capacitance per segment/common driver	–	500	5000	pF	–
SID156	LCD_{OFFSET}	Long-term segment offset	–	20	–	mV	–
SID157	I_{LCDOP1}	LCD system operating current Vbias = 5 V	–	2	–	mA	32 × 4 segments. 50 Hz. 25 °C
SID158	I_{LCDOP2}	LCD system operating current Vbias = 3.3 V	–	2	–		32 × 4 segments. 50 Hz. 25 °C

Table 21. LCD Direct Drive AC Specifications[8]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID159	F_{LCD}	LCD frame rate	10	50	150	Hz	–

Note

8. Guaranteed by characterization.

Memory

Table 22. Flash DC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID173	V_{PE}	Erase and program voltage	1.71	–	5.5	V	–

Table 23. Flash AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID174	$T_{ROWWRITE}$[9]	Row (block) write time (erase and program)	–	–	20	ms	Row (block) = 128 bytes
SID175	$T_{ROWERASE}$[9]	Row erase time	–	–	16		–
SID176	$T_{ROWPROGRAM}$[9]	Row program time after erase	–	–	4		–
SID178	$T_{BULKERASE}$[9]	Bulk erase time (32 KB)	–	–	35		–
SID180[10]	$T_{DEVPROG}$[9]	Total device program time	–	–	7	Seconds	–
SID181[10]	F_{END}	Flash endurance	100 K	–	–	Cycles	–
SID182[10]	F_{RET}	Flash retention. $T_A \le 55$ °C, 100 K P/E cycles	20	–	–	Years	–
SID182A[10]	–	Flash retention. $T_A \le 85$ °C, 10 K P/E cycles	10	–	–		–
SID256	TWS48	Number of Wait states at 48 MHz	2	–	–		CPU execution from Flash
SID257	TWS24	Number of Wait states at 24 MHz	1	–	–		CPU execution from Flash

System Resources

Power-on Reset (POR)

Table 24. Power On Reset (PRES)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.CLK#6	SR_POWER_UP	Power supply slew rate	1	–	67	V/ms	At power-up
SID185[10]	$V_{RISEIPOR}$	Rising trip voltage	0.80	–	1.5	V	–
SID186[10]	$V_{FALLIPOR}$	Falling trip voltage	0.70	–	1.4		–

Table 25. Brown-out Detect (BOD) for V_{CCD}

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID190[10]	$V_{FALLPPOR}$	BOD trip voltage in active and sleep modes	1.48	–	1.62	V	–
SID192[10]	$V_{FALLDPSLP}$	BOD trip voltage in Deep Sleep	1.11	–	1.5		–

Notes

[9] It can take as much as 20 milliseconds to write to Flash. During this time the device should not be Reset, or Flash operations will be interrupted and cannot be relied on to have completed. Reset sources include the XRES pin, software resets, CPU lockup states and privilege violations, improper power supply levels, and watchdogs. Make certain that these are not inadvertently activated.

[10] Guaranteed by characterization.

SWD Interface

Table 26. SWD Interface Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID213	F_SWDCLK1	3.3 V ≤ V_{DD} ≤ 5.5 V	–	–	14	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID214	F_SWDCLK2	1.71 V ≤ V_{DD} ≤ 3.3 V	–	–	7		SWDCLK ≤ 1/3 CPU clock frequency
SID215[11]	T_SWDI_SETUP	T = 1/f SWDCLK	0.25*T	–	–	ns	–
SID216[11]	T_SWDI_HOLD	T = 1/f SWDCLK	0.25*T	–	–		–
SID217[11]	T_SWDO_VALID	T = 1/f SWDCLK	–	–	0.5*T		–
SID217A[11]	T_SWDO_HOLD	T = 1/f SWDCLK	1	–	–		–

Internal Main Oscillator

Table 27. IMO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID218	I_{IMO1}	IMO operating current at 48 MHz	–	–	250	µA	–
SID219	I_{IMO2}	IMO operating current at 24 MHz	–	–	180	µA	–

Table 28. IMO AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID223	$F_{IMOTOL1}$	Frequency variation at 24, 32, and 48 MHz (trimmed)	–	–	±2	%	
SID226	$T_{STARTIMO}$	IMO startup time	–	–	7	µs	–
SID228	$T_{JITRMSIMO2}$	RMS jitter at 24 MHz	–	145	–	ps	–

Internal Low-Speed Oscillator

Table 29. ILO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID231[11]	I_{ILO1}	ILO operating current	–	0.3	1.05	µA	–

Table 30. ILO AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID234[11]	$T_{STARTILO1}$	ILO startup time	–	–	2	ms	–
SID236[11]	$T_{ILODUTY}$	ILO duty cycle	40	50	60	%	–
SID237	$F_{ILOTRIM1}$	ILO frequency range	20	40	80	kHz	–

Note

[11] Guaranteed by characterization.

Ordering Information

The PSoC 4000S part numbers and features are listed in the following table.

Table 35. PSoC 4000S Ordering Information

Category	MPN	Features												Package				
		Max CPU Speed (MHz)	Flash (KB)	SRAM (KB)	Opamp (CTBm)	CapSense	10-bit CSD ADC	12-bit SAR ADC	LP Comparators	TCPWM Blocks	SCB Blocks	Smart I/Os	GPIO	WLCSP (0.35-mm pitch)	24-Pin QFN	32-Pin QFN	40-Pin QFN	48-Pin TQFP
4024	CY8C4024FNI-S402	24	16	2	0	0	1	0	2	5	2	8	21	✔				
	CY8C4024LQI-S401	24	16	2	0	0	1	0	2	5	2	8	19		✔			
	CY8C4024LQI-S402	24	16	2	0	0	1	0	2	5	2	16	27			✔		
	CY8C4024LQI-S403	24	16	2	0	0	1	0	2	5	2	16	34				✔	
	CY8C4024AZI-S403	24	16	2	0	0	1	0	2	5	2	16	36					✔
	CY8C4024FNI-S412	24	16	2	0	1	1	0	2	5	2	8	21	✔				
	CY8C4024LQI-S411	24	16	2	0	1	1	0	2	5	2	8	19		✔			
	CY8C4024LQI-S412	24	16	2	0	1	1	0	2	5	2	16	27			✔		
	CY8C4024LQI-S413	24	16	2	0	1	1	0	2	5	2	16	34				✔	
	CY8C4024AZI-S413	24	16	2	0	1	1	0	2	5	2	16	36					✔
4025	CY8C4025FNI-S402	24	32	4	0	0	1	0	2	5	2	8	21	✔				
	CY8C4025LQI-S401	24	32	4	0	0	1	0	2	5	2	8	19		✔			
	CY8C4025LQI-S402	24	32	4	0	0	1	0	2	5	2	16	27			✔		
	CY8C4025AZI-S403	24	32	4	0	0	1	0	2	5	2	16	36					✔
	CY8C4025FNI-S412	24	32	4	0	1	1	0	2	5	2	8	21	✔				
	CY8C4025LQI-S411	24	32	4	0	1	1	0	2	5	2	8	19		✔			
	CY8C4025LQI-S412	24	32	4	0	1	1	0	2	5	2	16	27			✔		
	CY8C4025AZI-S413	24	32	4	0	1	1	0	2	5	2	16	36					✔
4045	CY8C4045FNI-S412	48	32	4	0	1	1	0	2	5	2	8	21	✔				
	CY8C4045LQI-S411	48	32	4	0	1	1	0	2	5	2	8	19		✔			
	CY8C4045LQI-S412	48	32	4	0	1	1	0	2	5	2	16	27			✔		
	CY8C4045AZI-S413	48	32	4	0	1	1	0	2	5	2	16	36					✔

The nomenclature used in the preceding table is based on the following part numbering convention:

Field	Description	Values	Meaning
CY8C	Cypress Prefix		
4	Architecture	4	PSoC 4
A	Family	0	4000 Family
B	CPU Speed	2	24 MHz
		4	48 MHz

Packaging

The PSoC 4000S will be offered in 48-pin TQFP, 40-pin QFN, 32-pin QFN, 24-pin QFN, and 25-ball WLCSP packages. Package dimensions and Cypress drawing numbers are in the following table.

Table 36. Package List

Spec ID#	Package	Description	Package Dwg
BID20	48-pin TQFP	7 × 7 × 1.4 mm height with 0.5-mm pitch	51-85135
BID27	40-pin QFN	6 × 6 × 0.6 mm height with 0.5-mm pitch	001-80659
BID34A	32-pin QFN	5 × 5 × 0.6 mm height with 0.5-mm pitch	001-42168
BID34	24-pin QFN	4 × 4 × 0.6 mm height with 0.5-mm pitch	001-13937
BID34F	25-ball WLCSP	2.02 × 1.93 × 0.48 mm height with 0.35-mm pitch	002-09957

Table 37. Package Thermal Characteristics

Parameter	Description	Package	Min	Typ	Max	Units
TA	Operating ambient temperature		–40	25	85	°C
TJ	Operating junction temperature		–40	–	100	°C
TJA	Package θ_{JA}	48-pin TQFP	–	73.5	–	°C/Watt
TJC	Package θ_{JC}	48-pin TQFP	–	33.5	–	°C/Watt
TJA	Package θ_{JA}	40-pin QFN	–	17.8	–	°C/Watt
TJC	Package θ_{JC}	40-pin QFN	–	2.8	–	°C/Watt
TJA	Package θ_{JA}	32-pin QFN	–	20.8	–	°C/Watt
TJC	Package θ_{JC}	32-pin QFN	–	5.9	–	°C/Watt
TJA	Package θ_{JA}	24-pin QFN	–	21.7	–	°C/Watt
TJC	Package θ_{JC}	24-pin QFN	–	5.6	–	°C/Watt
TJA	Package θ_{JA}	25-ball WLCSP	–	54.6	–	°C/Watt
TJC	Package θ_{JC}	25-ball WLCSP	–	0.5	–	°C/Watt

Table 38. Solder Reflow Peak Temperature

Package	Maximum Peak Temperature	Maximum Time at Peak Temperature
All	260 °C	30 seconds

Table 39. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-020

Package	MSL
All except WLCSP	MSL 3
25-ball WLCSP	MSL 1

Package Diagrams

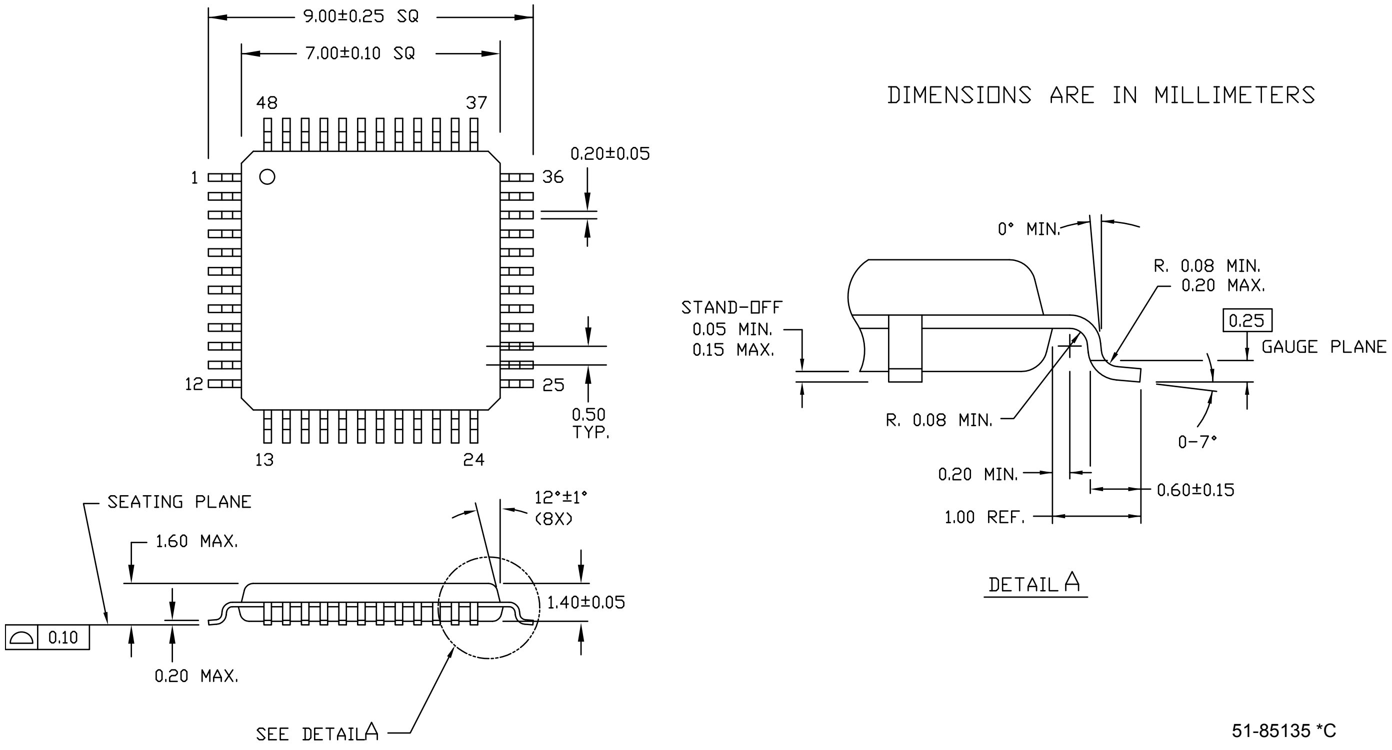
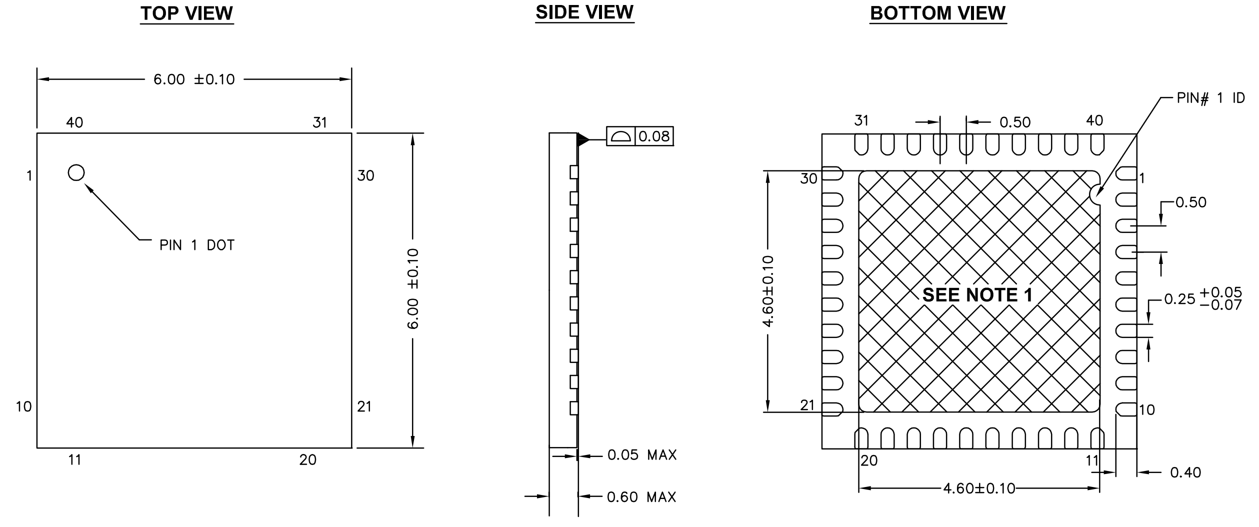


Figure 5. 48-pin TQFP Package Outline

Figure 6. 40-pin QFN Package Outline

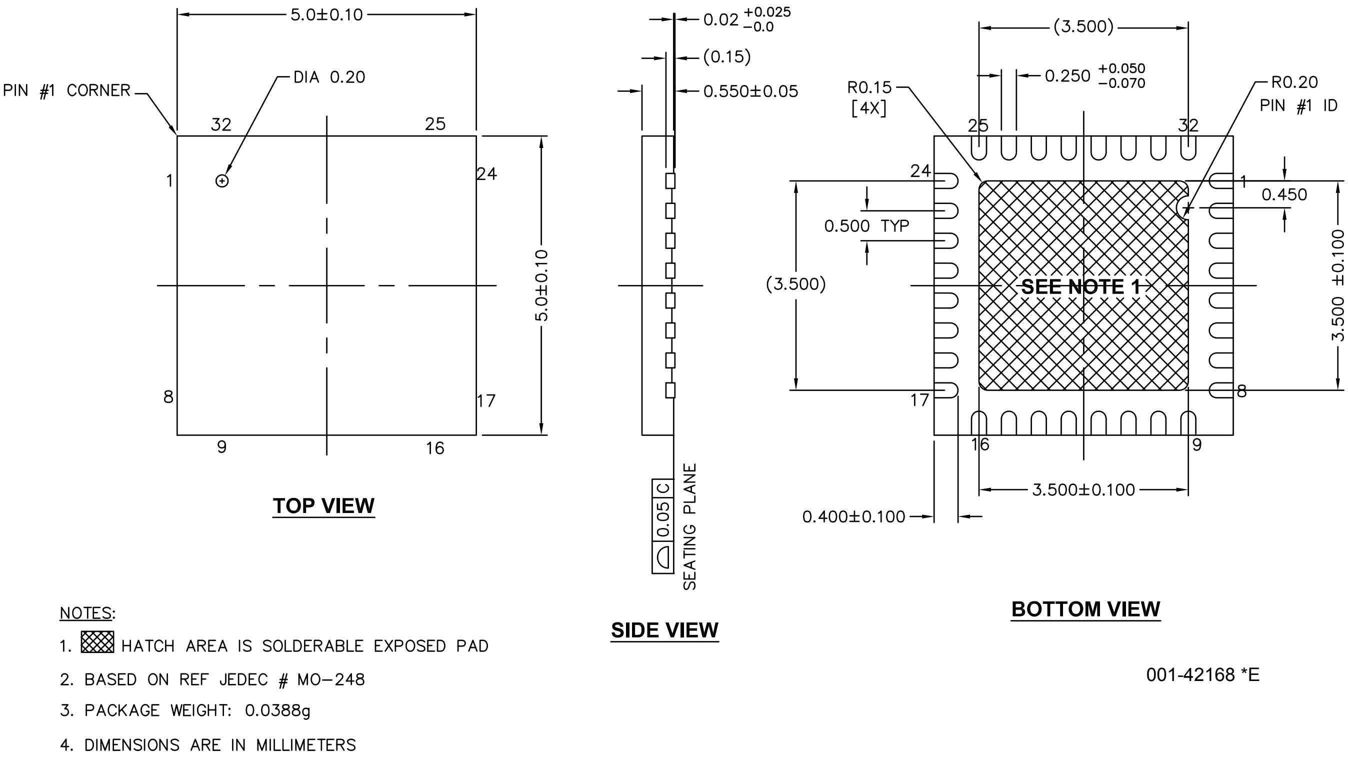


NOTES:

1. ▨ HATCH AREA IS SOLDERABLE EXPOSED PAD
2. REFERENCE JEDEC # MO-248
3. PACKAGE WEIGHT: 68 ±2 mg
4. ALL DIMENSIONS ARE IN MILLIMETERS

001-80659 *A

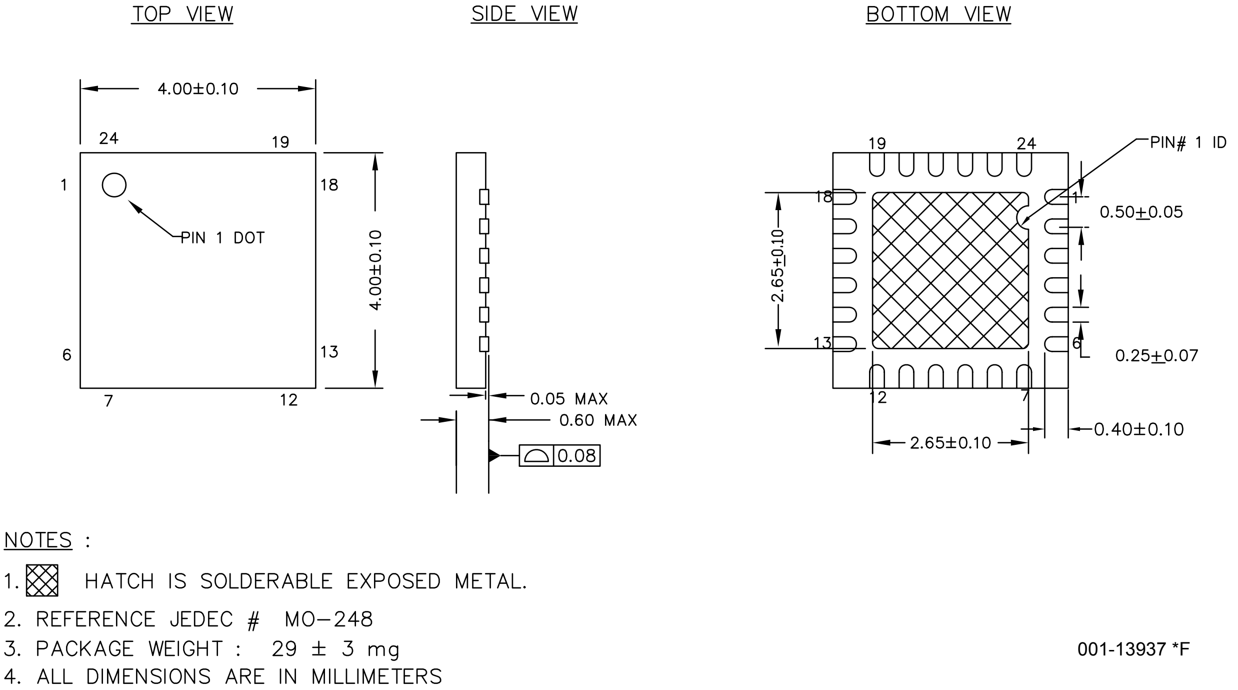
Figure 7. 32-pin QFN Package Outline



NOTES:

1. ▨ HATCH AREA IS SOLDERABLE EXPOSED PAD
2. BASED ON REF JEDEC # MO-248
3. PACKAGE WEIGHT: 0.0388g
4. DIMENSIONS ARE IN MILLIMETERS

Figure 8. 24-pin QFN Package Outline



NOTES :

1. ▨ HATCH IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC # MO-248
3. PACKAGE WEIGHT : 29 ± 3 mg
4. ALL DIMENSIONS ARE IN MILLIMETERS

The center pad on the QFN package should be connected to ground (VSS) for best mechanical, thermal, and electrical performance. If not connected to ground, it should be electrically floating and not connected to any other signal.

Acronyms

Table 40. Acronyms Used in this Document

Acronym	Description
abus	analog local bus
ADC	analog-to-digital converter
AG	analog global
AHB	AMBA (advanced microcontroller bus architecture) high-performance bus, an ARM data transfer bus
ALU	arithmetic logic unit
AMUXBUS	analog multiplexer bus
API	application programming interface
APSR	application program status register
ARM®	advanced RISC machine, a CPU architecture
ATM	automatic thump mode
BW	bandwidth
CAN	Controller Area Network, a communications protocol
CMRR	common-mode rejection ratio
CPU	central processing unit
CRC	cyclic redundancy check, an error-checking protocol
DAC	digital-to-analog converter, see also IDAC, VDAC
DFB	digital filter block
DIO	digital input/output, GPIO with only digital capabilities, no analog. See GPIO.
DMIPS	Dhrystone million instructions per second
DMA	direct memory access, see also TD
DNL	differential nonlinearity, see also INL
DNU	do not use
DR	port write data registers
DSI	digital system interconnect
DWT	data watchpoint and trace
ECC	error correcting code
ECO	external crystal oscillator
EEPROM	electrically erasable programmable read-only memory
EMI	electromagnetic interference
EMIF	external memory interface
EOC	end of conversion
EOF	end of frame
EPSR	execution program status register
ESD	electrostatic discharge

Table 40. Acronyms Used in this Document *(continued)*

Acronym	Description
ETM	embedded trace macrocell
FIR	finite impulse response, see also IIR
FPB	flash patch and breakpoint
FS	full-speed
GPIO	general-purpose input/output, applies to a PSoC pin
HVI	high-voltage interrupt, see also LVI, LVD
IC	integrated circuit
IDAC	current DAC, see also DAC, VDAC
IDE	integrated development environment
I^{2}C, or IIC	Inter-Integrated Circuit, a communications protocol
IIR	infinite impulse response, see also FIR
ILO	internal low-speed oscillator, see also IMO
IMO	internal main oscillator, see also ILO
INL	integral nonlinearity, see also DNL
I/O	input/output, see also GPIO, DIO, SIO, USBIO
IPOR	initial power-on reset
IPSR	interrupt program status register
IRQ	interrupt request
ITM	instrumentation trace macrocell
LCD	liquid crystal display
LIN	Local Interconnect Network, a communications protocol.
LR	link register
LUT	lookup table
LVD	low-voltage detect, see also LVI
LVI	low-voltage interrupt, see also HVI
LVTTL	low-voltage transistor-transistor logic
MAC	multiply-accumulate
MCU	microcontroller unit
MISO	master-in slave-out
NC	no connect
NMI	nonmaskable interrupt
NRZ	non-return-to-zero
NVIC	nested vectored interrupt controller
NVL	nonvolatile latch, see also WOL
opamp	operational amplifier
PAL	programmable array logic, see also PLD

Table 40. Acronyms Used in this Document *(continued)*

Acronym	Description
PC	program counter
PCB	printed circuit board
PGA	programmable gain amplifier
PHUB	peripheral hub
PHY	physical layer
PICU	port interrupt control unit
PLA	programmable logic array
PLD	programmable logic device, see also PAL
PLL	phase-locked loop
PMDD	package material declaration data sheet
POR	power-on reset
PRES	precise power-on reset
PRS	pseudo random sequence
PS	port read data register
PSoC®	Programmable System-on-Chip™
PSRR	power supply rejection ratio
PWM	pulse-width modulator
RAM	random-access memory
RISC	reduced-instruction-set computing
RMS	root-mean-square
RTC	real-time clock
RTL	register transfer language
RTR	remote transmission request
RX	receive
SAR	successive approximation register
SC/CT	switched capacitor/continuous time
SCL	I^2C serial clock
SDA	I^2C serial data
S/H	sample and hold
SINAD	signal to noise and distortion ratio
SIO	special input/output, GPIO with advanced features. See GPIO.
SOC	start of conversion
SOF	start of frame
SPI	Serial Peripheral Interface, a communications protocol
SR	slew rate
SRAM	static random access memory
SRES	software reset
SWD	serial wire debug, a test protocol

Table 40. Acronyms Used in this Document *(continued)*

Acronym	Description
SWV	single-wire viewer
TD	transaction descriptor, see also DMA
THD	total harmonic distortion
TIA	transimpedance amplifier
TRM	technical reference manual
TTL	transistor-transistor logic
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
UDB	universal digital block
USB	Universal Serial Bus
USBIO	USB input/output, PSoC pins used to connect to a USB port
VDAC	voltage DAC, see also DAC, IDAC
WDT	watchdog timer
WOL	write once latch, see also NVL
WRES	watchdog timer reset
XRES	external reset I/O pin
XTAL	crystal

Document Conventions

Units of Measure

Table 41. Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
dB	decibel
fF	femto farad
Hz	hertz
KB	1024 bytes
kbps	kilobits per second
Khr	kilohour
kHz	kilohertz
kΩ	kilo ohm
ksps	kilosamples per second
LSB	least significant bit
Mbps	megabits per second
MHz	megahertz
MΩ	mega-ohm
Msps	megasamples per second
µA	microampere
µF	microfarad
µH	microhenry
µs	microsecond
µV	microvolt
µW	microwatt
mA	milliampere
ms	millisecond
mV	millivolt
nA	nanoampere
ns	nanosecond
nV	nanovolt
Ω	ohm
pF	picofarad
ppm	parts per million
ps	picosecond
s	second
sps	samples per second
sqrtHz	square root of hertz
V	volt

Revision History

Description Title: PSoC® 4: PSoC 4000S Family Datasheet Programmable System-on-Chip (PSoC) Document Number: 002-00123				
Revision	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
**	4883809	WKA	08/28/2015	New datasheet
*A	4992376	WKA	10/30/2015	Updated Pinouts. Added $V_{DDD} \geq 2.2V$ at –40 °C under Conditions for specs SID247A, SID90, SID92. Updated Table 12. Updated Ordering Information.
*B	5037826	SLAN	12/08/2015	Changed datasheet status to Preliminary
*C	5104369	WKA	01/27/2016	Added Errata. Added 25 WLCSP package details. Updated theta J_A and J_C values for all packages.
*D	5139206	WKA	02/16/2016	Updated copyright information at the end of the document.
*E	5173961	WKA	03/15/2016	Updated Pinouts. Updated values for SID79, BID194. SID175, and SID176. Updated CSD and IDAC Specifications. Updated 10-bit CapSense ADC Specifications.
*F	5268662	WKA	05/12/2016	Updated Alternate Pin Functions. Updated the following specs: SID310, SID312, SID313, SID314, SID314C, SID314D, SID314E, SID315, SID315C, SID315D, SID315E, SID322A, SID322B, SIDA109. Removed Errata section. Updated the Cypress logo and copyright information based on the template.
*G	5330930	WKA	07/27/2016	Updated LCD Segment Drive. Updated SID60 conditions. Updated IDD specs. Corrected package dimensions for WLCSP package and added WLCSP MSL condition. Moved datasheet status to Final.
*H	5415365	WKA	09/14/2016	Added 40-pin QFN pin and package details. Updated IDD spec values in DC Specifications.
*I	5561833	WKA	01/09/2017	Changed PRGIO references to Smart I/O.
*J	5704046	GNKK	04/26/2017	Updated the Cypress logo and copyright information.